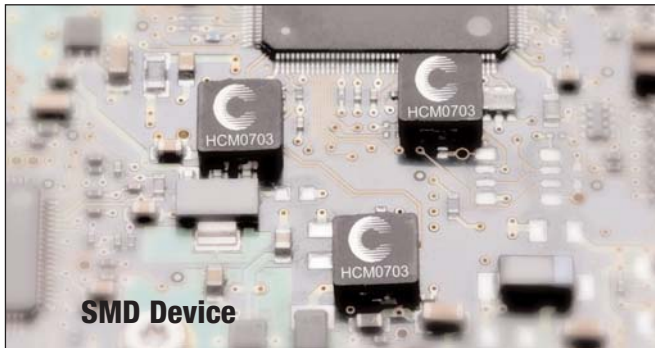


High Current, Power Inductors

HCM0703 Series



Description

- Halogen Free
- 125°C maximum total temperature operation
- 7.4 x 7.0 x 3.0mm maximum surface mount package
- Powder iron core material
- Magnetically shielded, low EMI
- High current carrying capacity, Low core losses
- Inductance range from 0.15μH to 10.0μH
- Current range from 3.2 to 52 Amps
- RoHS compliant

Applications

- Voltage Regulator Module (VRM)
- Multi-phase regulators
- Point-of-load modules
- Desktop and server VRMs and EVRDs
- Base station equipment
- Notebook regulators
- Battery power systems
- Graphics cards
- Data networking and storage systems

Environmental Data

- Storage temperature range: -55°C to +125 °C
- Operating temperature range: -55°C to +125°C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020D compliant

Packaging

- Supplied in tape and reel packaging, 1,500 parts per 13" diameter reel

Product Specifications

Part Number ⁶	OCL ¹ (μH) ±20%	FLL min, ² (μH)	I _{rms} ³ (Amps)	I _{sat} ⁴ @ 20°C (Amps)	DCR (mΩ) @ 20°C (Typical)	DCR (mΩ) @ 20°C (Maximum)	K-factor ⁵
HCM0703-R15-R	0.15	0.09	26.0	52.0	1.90	2.50	1610.3
HCM0703-R22-R	0.22	0.13	23.0	40.0	2.50	2.80	615.4
HCM0703-R47-R	0.47	0.28	17.5	26.0	4.00	4.20	430.2
HCM0703-R68-R	0.68	0.41	15.5	25.0	5.00	5.50	367.4
HCM0703-R82-R	0.82	0.49	13.0	24.0	6.70	8.00	286.2
HCM0703-1R0-R	1.00	0.60	11.0	22.0	9.00	10.0	259.7
HCM0703-1R5-R	1.50	0.90	9.00	18.0	14.0	15.0	175.7
HCM0703-2R2-R	2.20	1.32	8.00	14.0	18.0	20.0	163.6
HCM0703-3R3-R	3.30	1.98	6.00	13.5	28.0	30.0	158.2
HCM0703-4R7-R	4.70	2.82	5.50	10.0	37.0	40.0	118.1
HCM0703-6R8-R	6.80	4.08	4.50	8.00	54.0	60.0	106.8
HCM0703-8R2-R	8.20	4.92	4.00	7.50	64.0	68.0	95.3
HCM0703-100-R	10.0	6.00	3.20	7.00	70.5	77.6	81.2

1 Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.25V_{rms}, 0.0Adc, @ +20°C.

2 Full Load Inductance (FLL) Test Parameters: 100kHz, 0.25V_{rms}, I_{sat} @ +20°C.

3 I_{rms}: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.

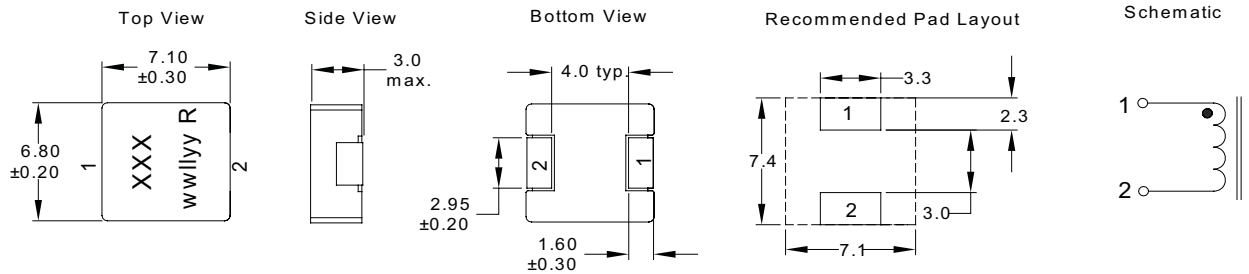
4 I_{sat}: Peak current for approximately 20% rolloff at +20°C.

5 K-factor: Used to determine B_{p-p} for core loss (see graph). B_{p-p} = K * L * ΔI. B_{p-p} (Gauss), K: (K-factor from table), L: (inductance in μH), ΔI (peak-to-peak ripple current in amps).

6 Part Number Definition: HCM0703-xxx-R

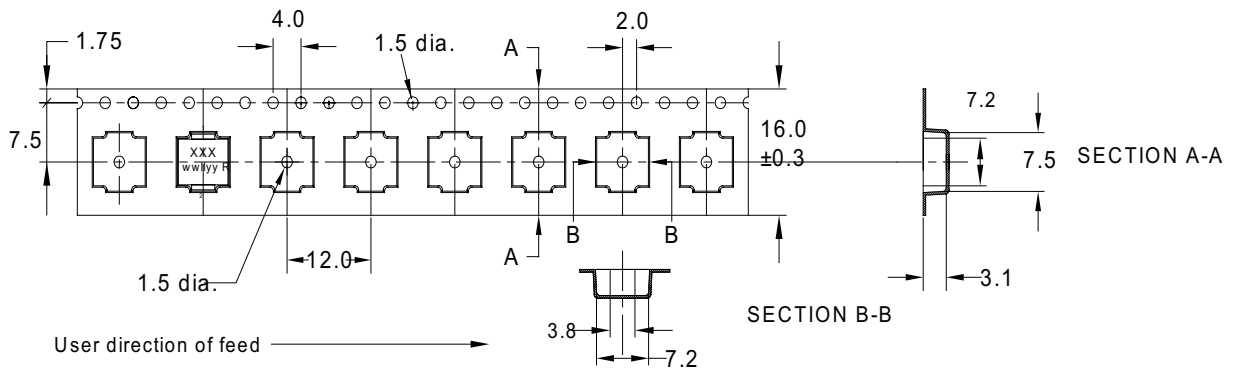
- HCM0703 = Product code and size
- xxx= Inductance value in μH, R = decimal point, If no R is present then 3rd digit equals number of zeros.
- "-R" suffix = RoHS compliant

Dimensions - mm



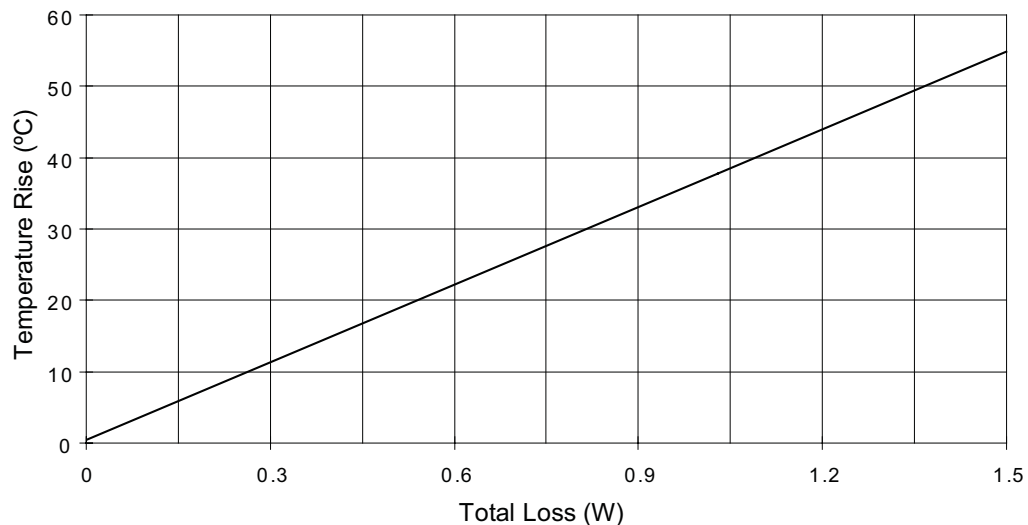
Part marking: xxx= Inductance value in uH, R= decimal point, If no R is present then last digit is # of zeroes wlllyy= Date code, R= Revision level
Tolerances are ± 0.3 unless other wise specified.

Packaging Information - mm



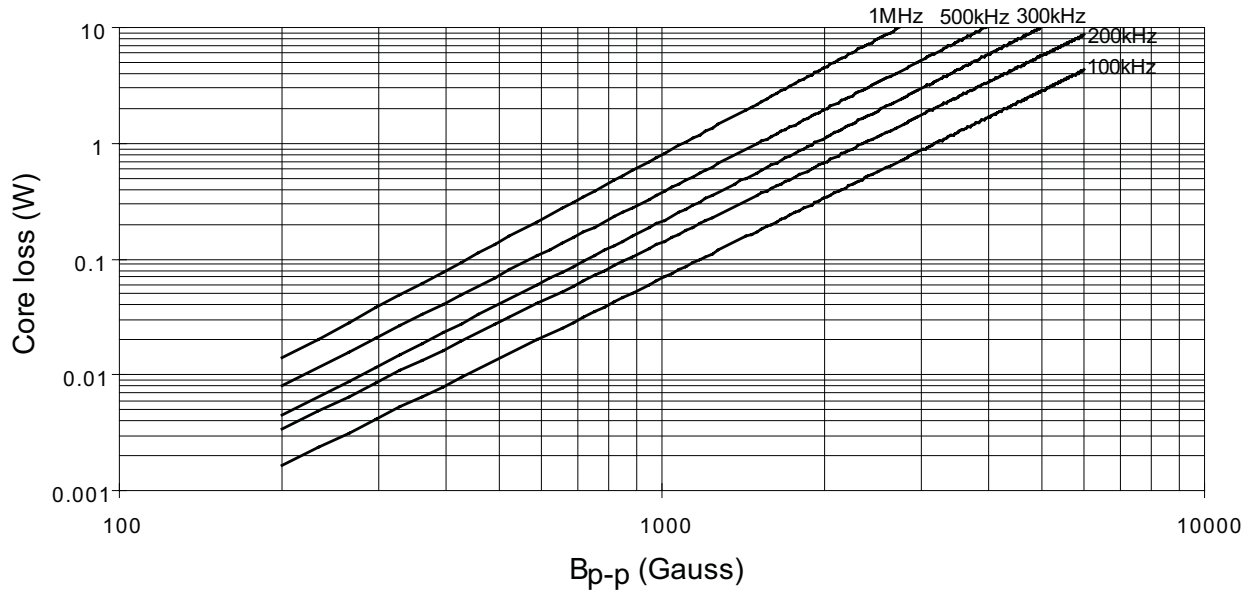
Supplied in tape-and-reel packaging, 1,500 parts per reel, 13" diameter reel.

Temperature Rise vs. Total Loss



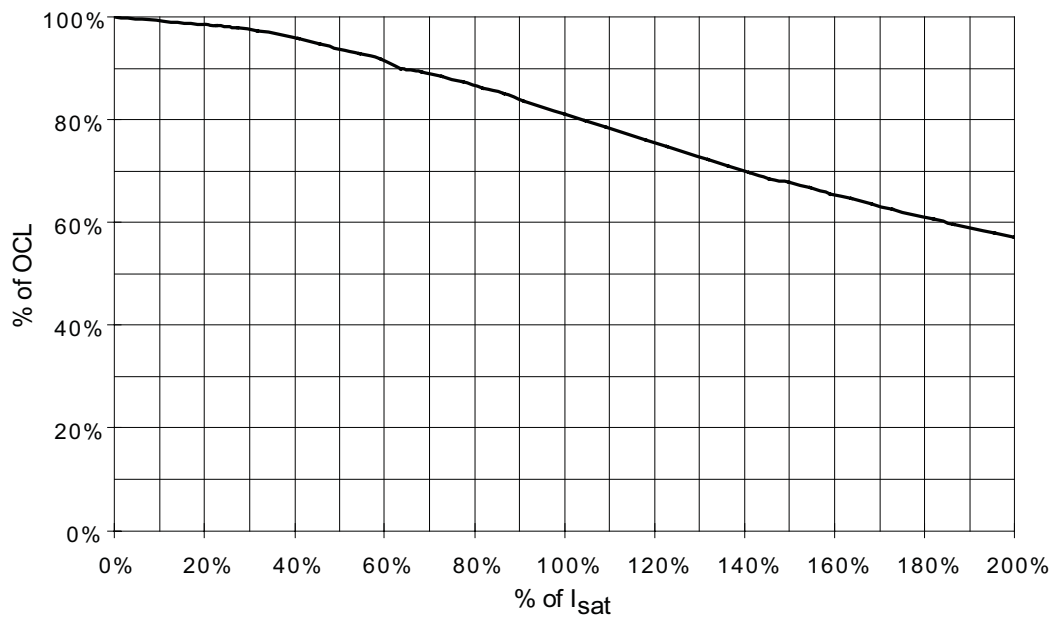
Core Loss

Core Loss vs. B_{p-p}



Inductance Characteristics

% of OCL vs % of I_{sat}





Solder Reflow Profile

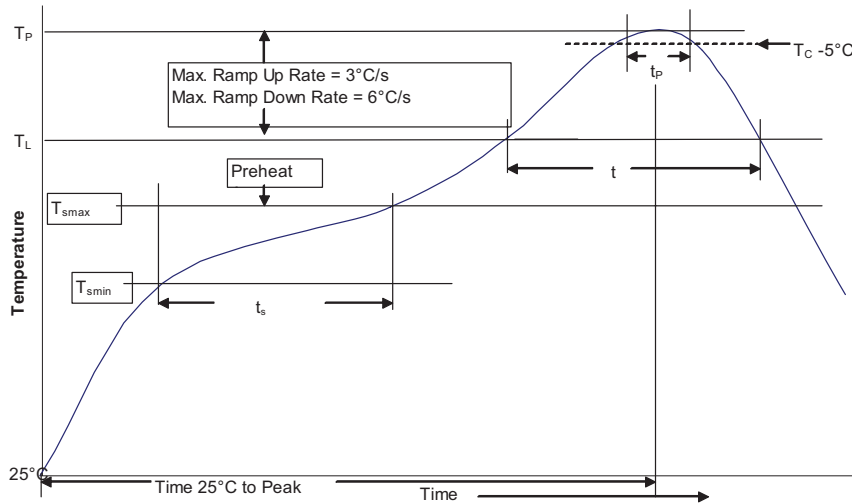


Table 1 - Standard SnPb Solder (T_c)

Package Thickness	Volume mm^3 <350	Volume mm^3 ≥ 350
<2.5mm	235°C	220°C
$\geq 2.5\text{mm}$	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_c)

Package Thickness	Volume mm^3 <350	Volume mm^3 350 - 2000	Volume mm^3 >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100°C	150°C
• Temperature max. (T_{smax})	150°C	200°C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_P	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_P)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_P to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

North America

Cooper Electronic Technologies
1225 Broken Sound Parkway NW
Suite F
Boca Raton, FL 33487-3533
Tel: 1-561-998-4100
Fax: 1-561-241-6640
Toll Free: 1-888-414-2645

Cooper Bussmann
P.O. Box 14460
St. Louis, MO 63178-4460
Tel: 1-636-394-2877
Fax: 1-636-527-1607

Europe

Cooper Electronic Technologies
Cooper (UK) Limited
Burton-on-the-Wolds
Leicestershire • LE12 5TH UK
Tel: +44 (0) 1509 882 737
Fax: +44 (0) 1509 882 786

Cooper Electronic Technologies
Avda. Santa Eulalia, 290
08223
Terrassa, (Barcelona), Spain
Tel: +34 937 362 812
+34 937 362 813
Fax: +34 937 362 719

Asia Pacific

Cooper Electronic Technologies
1 Jalan Kilang Timor
#06-01 Pacific Tech Centre
Singapore 159303
Tel: +65 278 6151
Fax: +65 270 4160

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